

A B S T R A C T

A METHOD AND APPARATUS FOR SEPARATING A PLATE OF
MATERIAL, IN PARTICULAR OF SEMICONDUCTOR MATERIAL, INTO
5 TWO WAFERS

The invention relates to a method of separating into
two wafers (2,4) a plate (1) of material for
manufacturing substrates for electronics, optics, or
10 optoelectronics, or for manufacturing microsystems, said
wafers being situated on either side of a plane of
weakness (6), the method being characterized in that it
comprises the steps consisting in:

- exerting a deformation force on at least one of
15 the wafers so as to cause the wafers (2, 4) to separate
from each other in a zone of the plate (1) at said plane
of weakness; and

- exerting guided separation movement on the wafers
(2, 4).

20 The invention also provides apparatus (100) for
implementing the method, which apparatus has gripping
members (30, 32) suitable for exerting said deformation
force and for performing said separation.

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Translation of the title and the abstract as they were when originally filed by the
35 Applicant. No account has been taken of any changes that may have been made
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